

CIPEL Distribution S.A.

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AUXILIARY DRY FILM CHEMISTRY



Developer K45 : highly concentrated solutions of potassium carbonate designed for development of all aqueous dry film resists and photoimageable solder masks.

Wide operational parameters : 1 liter of concentrate will develop 12 sq mtrs.

Developer K70 : highly concentrated solutions of potassium carbonate designed for development of all aqueous dry film resists and photoimageable solder masks.

Wide operational parameters : 1 liter of concentrate will develop 18 sq mtrs.

Ordyl Stripper 5600 : alkaline, fully aqueous, solvent free dry film stripper concentrate, designed to strip all commercially available aqueous dry film resist products. Ordyl Stripper 5600 with filtration system will strip approximately 15 – 20m² of 50µm aqueous resist per liter of strip solution. It can be used in conveyorized spray or immersion stripping systems.

Ordyl Stripper 5000 : alkaline, fully aqueous solvent free dry film stripper concentrate designed to strip all commercially available aqueous dry film resist products. Ordyl Stripper 5000 with filtration system will strip approximately 15 – 20m² of 50µm aqueous resist per liter of strip solution.

Dry Film Stripper 300 : highly alkaline liquid concentrate for removal of aqueous dry films and alkaline processable inks. Dry Film Stripper 300 is virtually odorless making its use in open dip tanks trouble free with no requirement for extraction.

SURFACE PREPARATION CHEMISTRY

Ordyl Antifoam C : highly concentrate liquid antifoam for use in the control of foam in alkaline dry film developing and stripping solutions. No silicone agents included.

Ordyl Antifoam T3 : lightly concentrated liquid antifoam for use in the control foam in alkaline dry film developing and stripping solutions. Ordyl Antifoam T3 is soluble in water up to a ratio of 1:10 to 1:20 making it ideal for dosing in feed and bleed systems. No silicone agents included.

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PLATING PROCESS CHEMISTRY

Technietch D-688TC ensures an excellent surface preparation with an optimum copper topography leading to improved performance of subsequent processes (dry film, soldermask, hot air solder levelling).

TechniEtch 1118 can be used in horizontal or vertical equipment and for various applications including surface treatment prior to resist, electrolytic and electroless copper plating, electroless nickel as well as many copper surfaces commonly used in connector and lead frame manufacturing processes.

Techniclean 688 : liquid acid cleaner specifically formulated to produce a clean slightly etched surface; it can remove oxides, fingerprints, light oils and other soils from copper or copper alloys. Techniclean 688 can be used in either soak or spray applications.

Acid Cleaner 100 can be used to degrease all common metal types with no effect, and can also be used to treat sensitive metals such as magnesium, aluminium and their alloys.

PLATING PROCESS CHEMISTRY

Acid Cleaner 230E is specifically formulated for cleaning copper surfaces in conveyORIZED spray machine. The use of Acid Cleaner 230E ensures excellent copper surface preparation for subsequent plating processes. Acid Cleaner 230E does not attack in any way Ordyl dry films.

Microetch 3100 is particularly effective in etching both electroless and electroplated copper surfaces prior to processing through the electroless nickel and immersion gold, as well as many copper surfaces commonly used in the connector industry.

Elgatin TL matte sulphate plating bath can be used to plate directly on copper, nickel, and nickel alloys such as Alloy 42 and Kovar.

CLEANING SOLUTIONS

CL-DF-ST-I-EE Acid Solution is a cleaning solution for the decontamination of dry film resist developing and stripping machines, and rinse modules (in connection with cleaning agent CL-MDF-ST-I-EE Alkaline Solution).

CL-MDF-ST-I-EE Alkaline Solution allows a comprehensive and thorough cleaning of resist stripping and developing machines (in connection with cleaning agent CL-DF-ST-I-EE Acid Solution).

LSL-ST-I-EE Solder-Mask Stripper : specially formulated for stripping solder mask even after the final curing.